

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DING WANG	12/27/2007
PENG-CHENG SONG	12/27/2007
CHANG-HONG LIU	12/27/2007
SHOU-SHAN FAN	12/27/2007

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11967124

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PATENT

500429628

REEL: 020303 FRAME: 0609

CH \$40.00 11967124

NAME OF SUBMITTER:

Frank R. Niranjana

Total Attachments: 2

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ASSIGNMENT

In consideration of value received, the receipt and sufficiency of which are hereby acknowledged, the undersigned ASSIGNOR(S)

1. Ding Wang, residing at Bei-Jing, China
2. Peng-Cheng Song, residing at Bei-Jing, China
3. Chang-Hong Liu, residing at Bei-Jing, China
4. Shou-shan Fan, residing at Bei-Jing, China

hereby sell(s), assign(s) and transfer(s) unto: Tsinghua University, a university having an office and place of business at No.1, Qinghua Yuan, Haidian District, Beijing City, China, P.R.C. and Hon Hai Precision Ind. Co., LTD. having a principal place of business at 66 Chung Shan Road, Tu-Cheng City, Taipei Hsien, Taiwan, R.O.C. hereafter designated "ASSIGNEE" the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100, in the invention and all patent applications including any and all divisions, continuations, substitutes, and reissues thereof, and all resulting patents, known as **METHOD FOR MAKING HIGH-DENSITY CARBON NANOTUBE ARRAY** for which the undersigned

[] previously executed --- Ser. No. _____ and filing date of _____
[x] is executing concurrently herewith

an application for Letters Patent of United States of America

AND the undersigned hereby authorize(s) and request(s) the United States Commissioner of Patents and Trademarks to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree(s) that the attorneys of record in said application, if any, shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree(s) to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE's full protection and title in and to the invention hereby transferred.

1.	<u>Ding Wang</u> Ding Wang inventor	<u>Dec. 27, 2007</u> Date	<u> </u> Witness
2.	<u>Pengcheng Song</u> Peng-Cheng Song inventor	<u>Dec. 27, 2007</u> Date	<u> </u> Witness
3.	<u>Chang-Hong Liu</u> Chang-Hong Liu inventor	<u>Dec. 27, 2007</u> Date	<u> </u> Witness
4.	<u>Shou-Shan Fan</u> Shou-Shan Fan inventor	<u>Dec. 27, 2007</u> Date	<u> </u> Witness
5.	<u> </u> inventor	<u> </u> Date	<u> </u> Witness
6.	<u> </u> inventor	<u> </u> Date	<u> </u> Witness
7.	<u> </u> inventor	<u> </u> Date	<u> </u> Witness
8.	<u> </u> inventor	<u> </u> Date	<u> </u> Witness